

ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit comprising a power supply wiring and a ground wiring and a decoupling capacitor formed between the power supply wiring and the ground wiring, wherein
5 at least one electrode of the decoupling capacitor consists of a shield layer formed in a plane shape on a semiconductor substrate, and the shield layer is electrically connected directly to the semiconductor substrate and is fixed to a power supply potential or the ground potential.